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ABSTRACT OF THE DISCLOSURE

Chips C which have already been diced are attached to a ring frame F using an adhesive sheet, and a protective sheet S1 is attached to a circuit pattern surface of the chips C. The chips C, along with a ring frame F, are held in place on a table 27 of a protective sheet peeling apparatus 20. A supply portion for an adhesive tape T is disposed in the vicinity of a table 24, and the supplied adhesive tape T is attached to the protective sheet S1. When the protective sheet S1 is peeled from the circuit pattern surface, peeling starts from corner portions of the chips C or opposing corner positions by pulling the adhesive tape T.